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Vishay Siliconix

Dual P-Channel 12-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | | | |
|---------------------|--|--------------------|-----------------------|--|--|--|--|--|
| V _{DS} (V) | $R_{DS(on)}$ (Ω) | I _D (A) | Q _g (Typ.) | | | | | |
| | $0.061 \text{ at V}_{GS} = -4.5 \text{ V}$ | - 4.5 ^a | | | | | | |
| - 12 | 0.081 at $V_{GS} = -2.5 \text{ V}$ | - 4.5 ^a | 8.2 nC | | | | | |
| | 0.115 at V _{GS} = - 1.8 V | - 4.5 ^a | | | | | | |

FEATURES

- Halogen-free According to IEC 61249-2-21
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area
 - Low On-Resistance

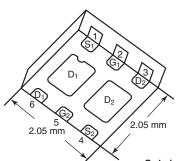
APPLICATIONS

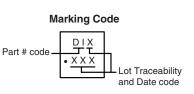
Devices



ROHS COMPLIANT HALOGEN FREE

PowerPAK SC-70-6 Dual





G_1 G_2 G_2

Load Switch, PA Switch and Battery Switch for Portable

Ordering Information: SiA913ADJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS | S T _A = 25 °C, unles | ss otherwise not | ed | | | |
|--|--|-----------------------------------|-----------------------|------|--|--|
| Parameter | | Symbol | Limit | Unit | | |
| Drain-Source Voltage | | V _{DS} | - 12 | V | | |
| Gate-Source Voltage | | V_{GS} | ± 8 | v | | |
| | T _C = 25 °C | | - 4.5 ^a | | | |
| Continuous Drain Current (T _J = 150 °C) | T _C = 70 °C | 1- | - 4.5 ^a | | | |
| Continuous Diam Current (1) = 130 C) | T _A = 25 °C | I _D | - 4.3 ^{b, c} | | | |
| | T _A = 70 °C | | - 3.8 ^{b, c} | Α | | |
| Pulsed Drain Current | | I _{DM} | - 15 | | | |
| Continuous Source-Drain Diode Current | T _C = 25 °C | I _S | - 4.5 ^a | | | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | 'S | - 1.6 ^{b, c} | 1 | | |
| | T _C = 25 °C | | 6.5 | | | |
| Maximum Power Dissipation | T _C = 70 °C | P _D | 5 | w | | |
| Maximum rower Dissipation | T _A = 25 °C | ' U | 1.9 ^{b, c} | 7 " | | |
| | T _A = 70 °C | | 1.2 ^{b, c} | | | |
| Operating Junction and Storage Temperature Ra | ange | T _J , T _{stg} | - 55 to 150 | °C | | |
| Soldering Recommendations (Peak Temperature | e) ^{d, e} | | 260 | 7 ~ | | |

| THERMAL RESISTANCE RATINGS | | | | | | | | | |
|---|--------------|------------|---------|---------|------|--|--|--|--|
| Parameter | | Symbol | Typical | Maximum | Unit | | | | |
| Maximum Junction-to-Ambient ^{b, f} | t ≤ 5 s | R_{thJA} | 52 | 65 | °C/W | | | | |
| Maximum Junction-to-Case (Drain) | Steady State | R_{thJC} | 12.5 | 16 |] | | | | |

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 110 °C/W.

SiA913ADJ

Vishay Siliconix



| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | | | | |
|---|-------------------------|--|-------|--------|-------|-------|--|--|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | | | |
| Static | | | | ı | ı | ı | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$ | - 12 | | | V | | | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = - 250 μA | | - 3.1 | | mV/°C | | | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 2.4 | | | | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 0.4 | | - 1 | V | | | |
| Gate-Source Leakage | I_{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ± 100 | nA | | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$ | | | - 1 | μΑ | | | |
| Zero Gate voltage Diam Current | טיטטא | V_{DS} = - 12 V, V_{GS} = 0 V, T_J = 55 °C | | | - 10 | | | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le$ - 5 V, $V_{GS} =$ - 4.5 V | - 10 | | | Α | | | |
| | | V _{GS} = - 4.5 V, I _D = - 3.6 A | 0.050 | 0.061 | | | | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = -2.5 \text{ V}, I_D = -3.2 \text{ A}$ | | 0.066 | 0.081 | Ω | | | |
| | | V _{GS} = - 1.8 V, I _D = - 1 A | | 0.093 | 0.115 | | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 6 V, I _D = - 3.6 A | | 11 | | S | | | |
| Dynamic ^b | | | | 1 | | l. | | | |
| Input Capacitance | C _{iss} | | | 590 | | | | | |
| Output Capacitance | C _{oss} | $V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 280 | | pF | | | |
| Reverse Transfer Capacitance | C _{rss} | 20 · G0 · | | 250 | | | | | |
| | | V _{DS} = -6 V, V _{GS} = -8 V, I _D = -4.5 A | | 13.1 | 20 | | | | |
| Total Gate Charge | Q_g | DG - 7 GG - 7 D | | 8.2 | 12.5 | nC | | | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.5 \text{ A}$ | | 1.2 | | | | | |
| Gate-Drain Charge | Q _{gd} | | | 2.8 | | | | | |
| Gate Resistance | R _g | f = 1 MHz | | 10 | | Ω | | | |
| Turn-On Delay Time | t _{d(on)} | | | 20 | 30 | | | | |
| Rise Time | t _r | $V_{DD} = -6 \text{ V}, R_1 = 1.6 \Omega$ | | 25 | 40 | - | | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -3.8 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$ | | 30 | 45 | | | | |
| Fall Time | t _f | g | | 20 | 30 | | | | |
| Turn-On Delay Time | t _{d(on)} | | | 8 | 15 | ns | | | |
| Rise Time | t _r | $V_{DD} = -6 \text{ V}, R_1 = 1.6 \Omega$ | | 12 | 20 | | | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong -3.8 \text{ A}, V_{GEN} = -8 \text{ V}, R_q = 1 \Omega$ | | 25 | 40 | | | | |
| Fall Time | t _f | SERV 9 | | 18 | 30 | | | | |
| Drain-Source Body Diode Characterist | | | | 1 | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 4.5 | | | | |
| Pulse Diode Forward Current | I _{SM} | | | | 10 | A | | | |
| Body Diode Voltage | V _{SD} | I _S = - 3.8 A, V _{GS} = 0 V | | - 0.85 | - 1.2 | V | | | |
| Body Diode Reverse Recovery Time | t _{rr} | 3 , - G 3 | | 30 | 60 | ns | | | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 12 | 24 | nC | | | |
| Reverse Recovery Fall Time | t _a | $I_F = -3.8 \text{ A}, dI/dt = 100 A/\mu s, T_J = 25 ^{\circ} C$ | | 16 | | - ns | | | |
| Reverse Recovery Rise Time | | | | 14 | | | | | |
| neverse necovery filse fille | t _b | | | 14 | | | | | |

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

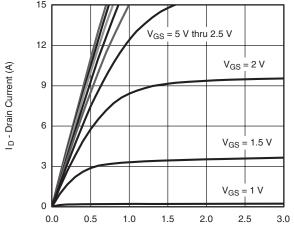
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.



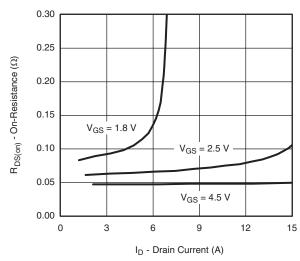
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

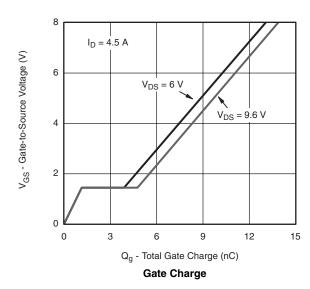


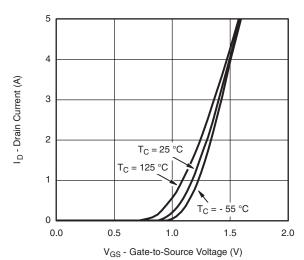
V_{DS} - Drain-to-Source Voltage (V)

Output Characteristics

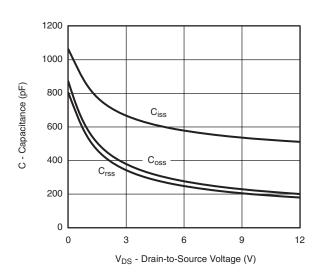


On-Resistance vs. Drain Current and Gate Voltage

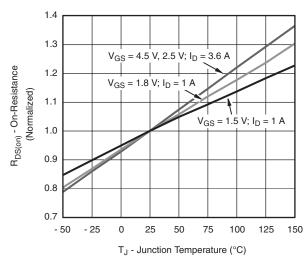




Transfer Characteristics



Capacitance



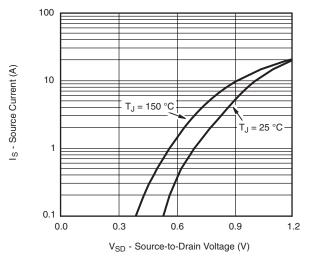
On-Resistance vs. Junction Temperature

SiA913ADJ

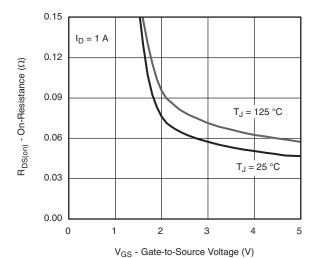
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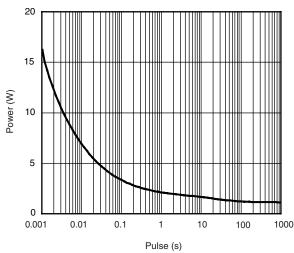
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



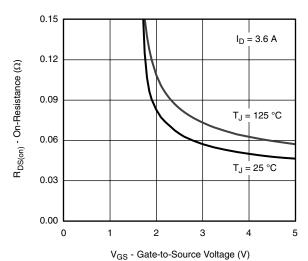
Soure-Drain Diode Forward Voltage



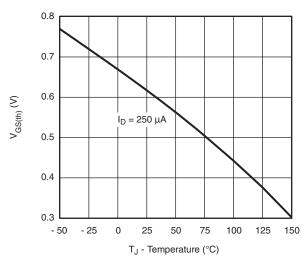
On-Resistance vs. Gate-to-Source Voltage



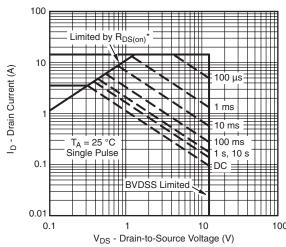
Single Pulse Power, Junction-to-Ambient



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

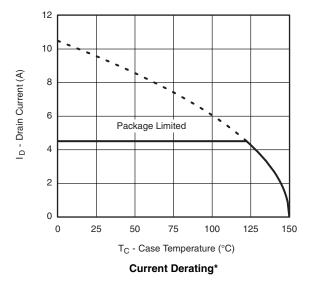
Safe Operating Area, Junction-to-Ambient

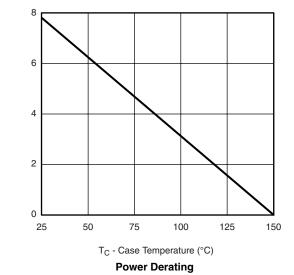
Power Dissipation (W)



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





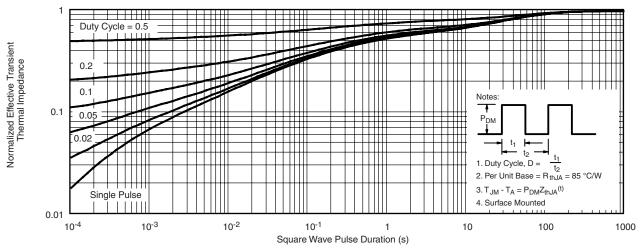
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

SiA913ADJ

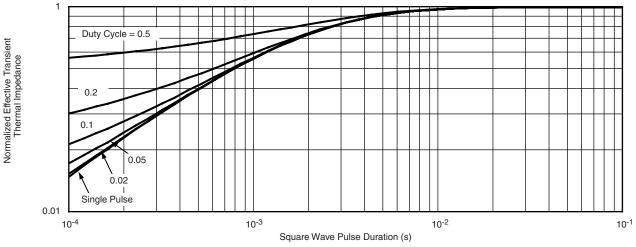
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

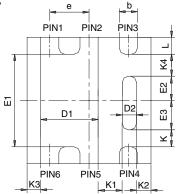
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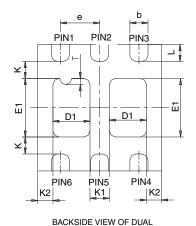




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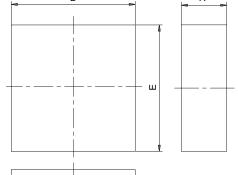
PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

Α





- 1. All dimensions are in millimeters
 2. Package outline exclusive of mold flash and metal burr
 3. Package outline inclusive of plating

| | | SINGLE PAD | | | | | | DUAL PAD | | | | | |
|--------------------------------|-------------|------------|-------|-----------|-----------|-----------|-------------|-----------|-------|-----------|-----------|-------|--|
| DIM | MILLIMETERS | | | INCHES | | | MILLIMETERS | | | INCHES | | | |
| | Min | Nom | Max | Min | Nom | Max | Min | Nom | Max | Min | Nom | Max | |
| Α | 0.675 | 0.75 | 0.80 | 0.027 | 0.030 | 0.032 | 0.675 | 0.75 | 0.80 | 0.027 | 0.030 | 0.032 | |
| A 1 | 0 | - | 0.05 | 0 | - | 0.002 | 0 | - | 0.05 | 0 | - | 0.002 | |
| b | 0.23 | 0.30 | 0.38 | 0.009 | 0.012 | 0.015 | 0.23 | 0.30 | 0.38 | 0.009 | 0.012 | 0.015 | |
| С | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 | |
| D | 1.98 | 2.05 | 2.15 | 0.078 | 0.081 | 0.085 | 1.98 | 2.05 | 2.15 | 0.078 | 0.081 | 0.085 | |
| D1 | 0.85 | 0.95 | 1.05 | 0.033 | 0.037 | 0.041 | 0.513 | 0.613 | 0.713 | 0.020 | 0.024 | 0.028 | |
| D2 | 0.135 | 0.235 | 0.335 | 0.005 | 0.009 | 0.013 | | | | | | | |
| Е | 1.98 | 2.05 | 2.15 | 0.078 | 0.081 | 0.085 | 1.98 | 2.05 | 2.15 | 0.078 | 0.081 | 0.085 | |
| E1 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 | 0.85 | 0.95 | 1.05 | 0.033 | 0.037 | 0.041 | |
| E2 | 0.345 | 0.395 | 0.445 | 0.014 | 0.016 | 0.018 | | | | | | | |
| E3 | 0.425 | 0.475 | 0.525 | 0.017 | 0.019 | 0.021 | | | | | | | |
| е | | 0.65 BSC | | | 0.026 BSC | | | 0.65 BSC | | | 0.026 BSC | | |
| K | | 0.275 TYP | | | 0.011 TYP | l | 0.275 TYP | | | 0.011 TYP | | | |
| K1 | | 0.400 TYP | | | 0.016 TYP | | | 0.320 TYP | | | 0.013 TYP | | |
| K2 | | 0.240 TYP | | 0.009 TYP | | 0.252 TYP | | 0.010 TYP | | | | | |
| К3 | | 0.225 TYP | | 0.009 TYP | | | | | | | | | |
| K4 | | 0.355 TYP | | 0.014 TYP | | | | | • | | | | |
| L | 0.175 | 0.275 | 0.375 | 0.007 | 0.011 | 0.015 | 0.175 | 0.275 | 0.375 | 0.007 | 0.011 | 0.015 | |
| Т | | | | | | | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 | |
| FCN: C-07431 - Rev C 06-Aug-07 | | | | | | | | | | | | | |

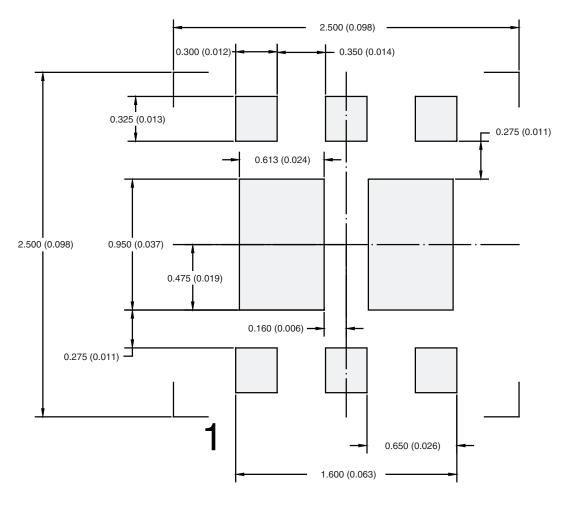
ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934

Document Number: 73001 06-Aug-07

VISHAY.

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm (inches)

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